

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT:	Okada	CONF. NO.:	4969
PATENT No.	7,432,595	ART UNIT:	2822
U. S. FILING DATE:	June 7, 2007	EXAMINER:	Potter, Roy K.
TITLE:	SYSTEM AND METHOD TO REDUCE METAL SERIES RESISTANCE OF BUMPED CHIP		

Mail Stop ISSUE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE TO INTERVIEW SUMMARY UNDER M.P.E.P. § 713.04

In reply to the Interview Summary mailed from the United States Patent and Trademark Office on January 23, 2009, Applicant respectfully requests entry of this Response. Applicant thanks the Examiner for participating in a telephone interview with Applicant's undersigned representative held on August 14, 2008. Applicant respectfully submits that the Interview Summary accurately reflects the discussions of August 14, 2008. No further supplementation is required.

No fees are believed necessary for filing this Response to Interview Summary. However, if any fees are due, the Director is hereby authorized to charge such fees to our Deposit Account No. 07-1700, under Order No. GWS-005.

Respectfully submitted,

Date: February 23, 2009
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